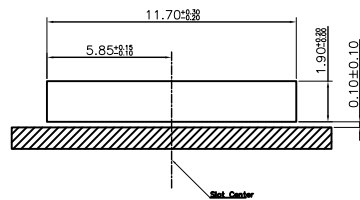
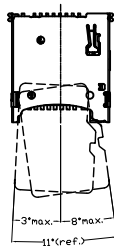


Recommended PCB Layout
Top View (Tolerance 0.05)

- Pad Area
- Other Component Keepout Area
- No Pattern Area



Recommended ID Dimension



Card Insertion Guide Angle

	Card Detect Switch
Card Uninsertion	Open
Card Half Insertion	Open
Card Insertion	Close
Open	Close

Pin No.	Pin Assignment (microSD Card)	Pin Assignment (UHS-II microSD Card)	Pin Assignment (microSD Express Card)
P1	Micro SD DAT2	Micro SD DAT2	Micro SD DAT2
P2	Micro SD CD/DAT3	Micro SD CD/DAT3	Micro SD CD/DAT3
P3	Micro SD CMD	Micro SD CMD	Micro SD CMD
P4	Micro SD VDD1	Micro SD VDD1	Micro SD VDD1
P5	Micro SD CLK	Micro SD CLK	Micro SD CLK
P6	Micro SD VSS	Micro SD VSS	Micro SD VSS
P7	Micro SD DAT0/RCLK+	Micro SD DAT0/RCLK+	Micro SD DAT0/RCLK+
P8	Micro SD DAT1/RCLK-	Micro SD DAT1/RCLK-	Micro SD DAT1/RCLK-
P9	Micro SD VDD2	Micro SD VDD2	Micro SD VDD2
P10	Micro SD VSS	Micro SD VSS	Micro SD VSS
P11	Micro SD D0+	PCIE Tx +	PCIE Tx +
P12	Micro SD D0-	PCIE Tx -	PCIE Tx -
P13	Micro SD VSS	Micro SD VSS	Micro SD VSS
P14	Micro SD D1-	PCIE Rx -	PCIE Rx -
P15	Micro SD D1+	PCIE Rx +	PCIE Rx +
P16	Micro SD VSS	VSS	VSS
P17	Micro SD SWO	VDD3	VDD3
P18	Micro SD CD	Micro SD CD	Micro SD CD
P19	Shielding GND	Shielding GND	Shielding GND
P20	Shielding GND	Shielding GND	Shielding GND
P21	Shielding GND	Shielding GND	Shielding GND
P22	Shielding GND	Shielding GND	Shielding GND
P23	Shielding GND	GND	GND

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
6	Link	1Pcs	SUS304-H T=0.25±0.05mm	Not plating
5	Spring	1Pcs	SVP-3	Underplating Ni
4	Slide	1Pcs	PA9T UL94V-0, Black	
3	Terminal	1Pcs	Copper Alloy (C3610R-2H1T=0.08±0.05mm)	Contact area: Gold 50" min. Solder tail: Matted TIN 80" min. Over Ni 50u" min.
2	Housing	1Set	High Temperature Thermoplastic CLDP UL 94V-0	Black
1	Shell	1Pcs	SUS304-H T=0.25±0.05mm	Underplating Ni overall 50u" min

- Note:
- Material:
 - 1-1. Plastic: LCP, Black, UL94V-0
 - 1-2. Contact: Copper Alloy
 - 1-3. Shell: Stainless Steel
 - Plating:
 - 2-1. Contact:
 - Contact Area: Au 5u" min, Plating Over Ni 50u" min.
 - Solder tail: Matted TIN 80u" min. Over Ni 50u" min.
 - 2-2. Shell:
 - Solderability Ni 50u" min. Over All
 - Contact And Tail Coplanarity To Be 0.10mm max.

深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2' X.X' ±0.5' UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: TF 7.1 PUSH 1.2TH
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW189-TF23-127B
APPROVED BY: 邱敏	DATE : 2014-02-23		